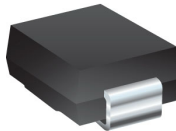


MATERIAL DECLARATION SHEET



Package Type	SMC (DO-214AB) 5.0SMDJxxxA-R					
Product Line	Thyristor Surge Protectors					
Compliance Date	03/10/2025					
RoHS Compliant	Yes	Terminal	e3	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy resin	0.10635	Fused Silica	60676-86-0	71.985	29.639	41.173
				Epoxy Resin	29690-82-2	15.032	6.189	
				Crystalline Silica	14808-60-7	6.711	2.763	
				Phenol Resin	9003-35-4	5.782	2.380	
				Carbon Black	1333-86-4	0.490	0.202	
2	Leadframe	Copper Alloy	0.09491	Copper	7440-50-8	99.865	36.709	36.744
				Iron	7439-89-6	0.100	0.032	
				Phosphorus	7723-14-0	0.033	0.002	
				Lead	7439-92-1	0.002	0.001	
3	Clip	Copper Alloy	0.03330	Copper	7440-50-8	99.865	12.8795	12.892
				Iron	7439-89-6	0.100	0.0113	
				Phosphorus	7723-14-0	0.033	0.0009	
				Lead	7439-92-1	0.002	0.0003	
4	Chip	Silicon	0.01279	Silicon	7440-21-3	88.004	4.3580	4.952
				Aluminum	7429-90-5	4.716	0.2335	
				Nickel	7440-02-0	6.856	0.3395	
				Gold	7440-57-5	0.424	0.0210	
5	Die attach	Solder paste	0.00806	*Lead	7439-92-1	92.500	2.9438	3.120
				Tin	7440-31-5	5.000	0.1026	
				Silver	7440-22-4	2.500	0.0736	
6	Terminal Finish	Tin	0.00289	Tin	7440-31-5	100.000	1.119	1.119
Total weight			0.25830					

* 7(a) Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.

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